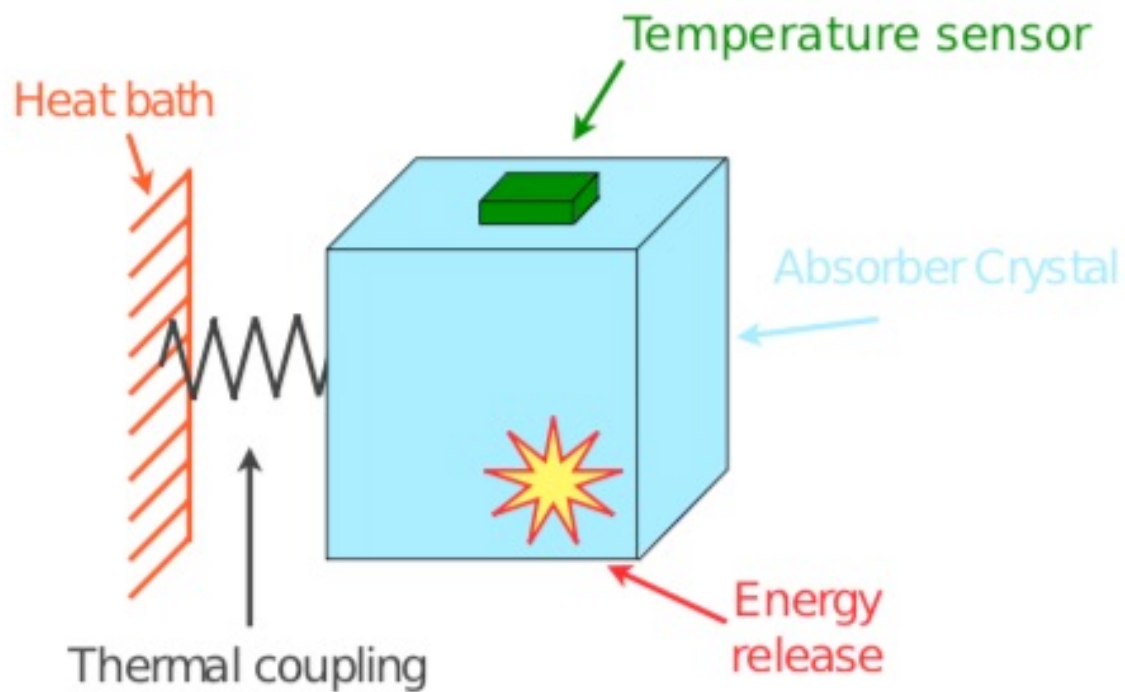


低温粒子探测器工作原理及声子热化



$$\Delta T(t) = \frac{E}{C} e^{-t/\tau} \quad \text{with} \quad \tau \equiv \frac{C}{G}$$

When a particle releases some energy in the absorber, phonons out of the thermodynamic equilibrium are produced (**athermal phonons**). These phonons degrade their energy via several interactions and reach a new thermal equilibrium distribution.

Bolometric detectors sensitive to **athermal phonons** are characterized by response times of the order of μs (**'fast' detectors**). Instead, if the temperature sensor response time is higher than the phonons thermalization time, **it will detect mainly the thermalized phonons, thus measuring the actual temperature of the absorber; in this case the device is a 'slow' detector and it acts as an ideal calorimeter.**

声子热化

将沉积的粒子能量转化为热声子的过程复杂，主要热化过程可以通过**核和电子通道**，即粒子通过与**原子核/电子**的**散射**与吸收体相互作用，进而将能量转换为声子；

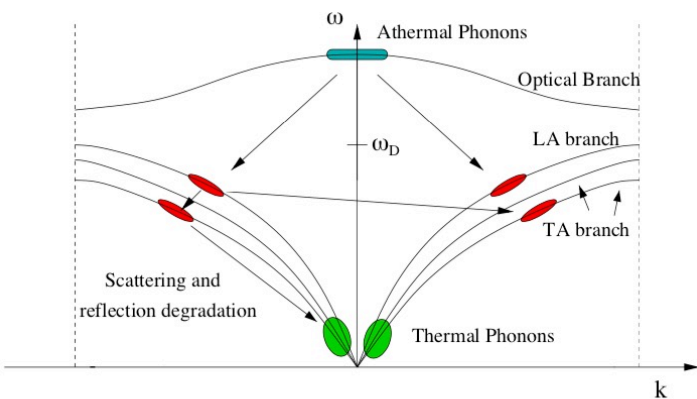
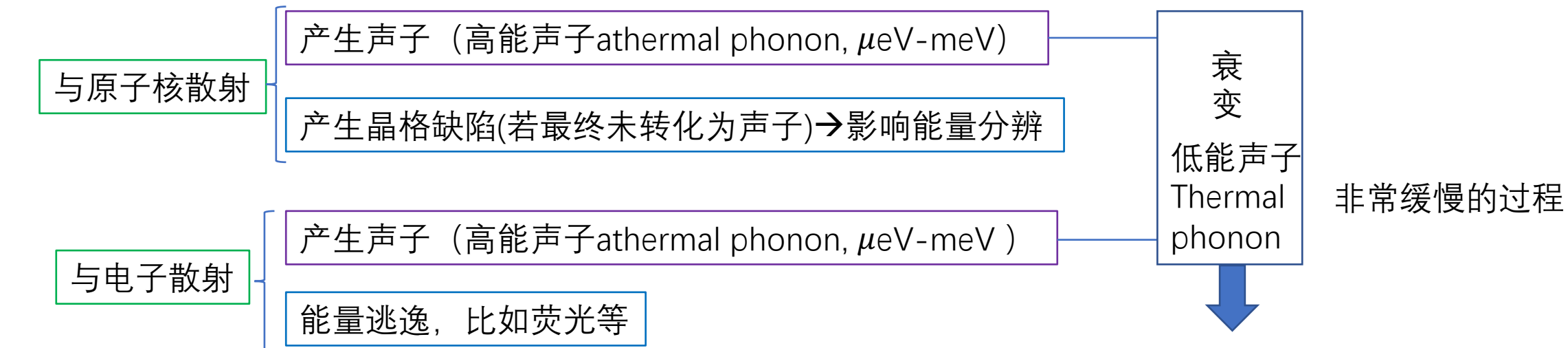


FIGURE 3.3: Athermal phonon thermalization model.

最后，声子平均自由程大于晶体尺寸，晶体表面/边沿反射

两种传感器

收集/感受声子的器件，热信号转化为电信号

TES，超导转变边沿传感器，快速传感器'fast' sensor (μs), can detect athermal phonon

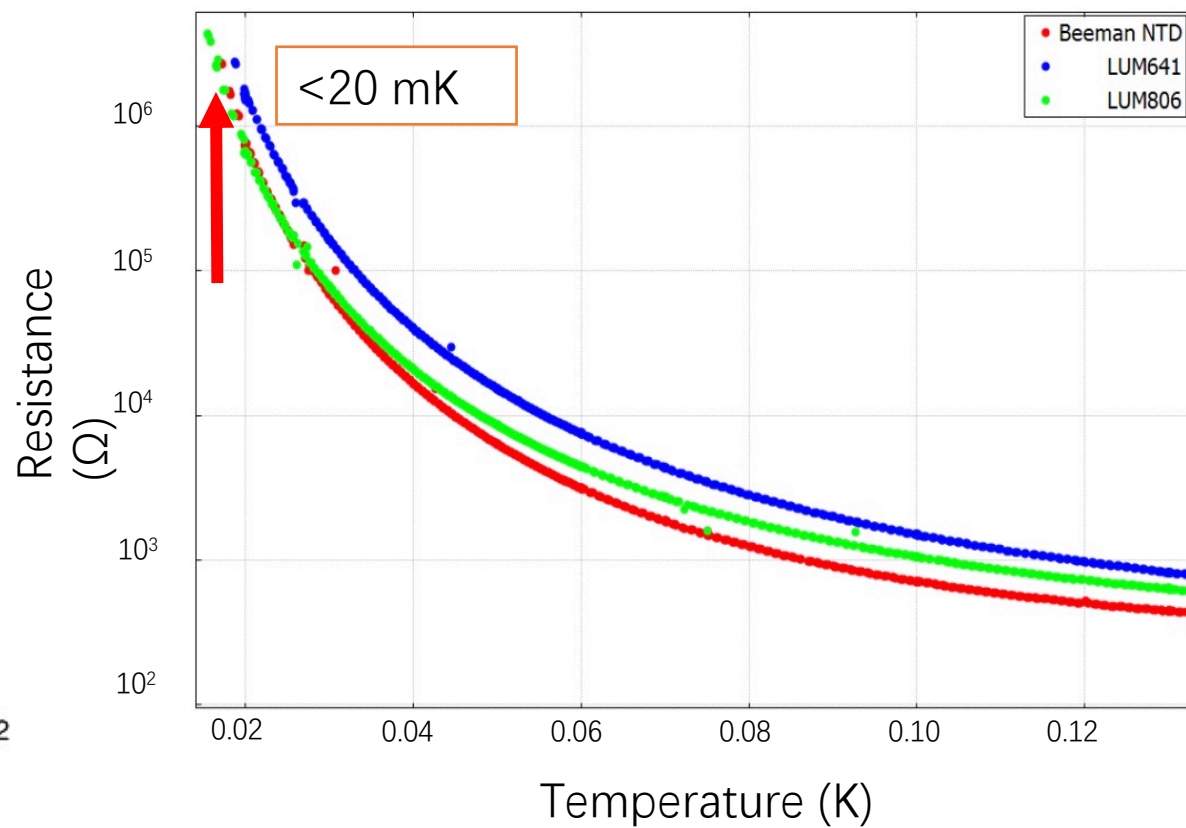
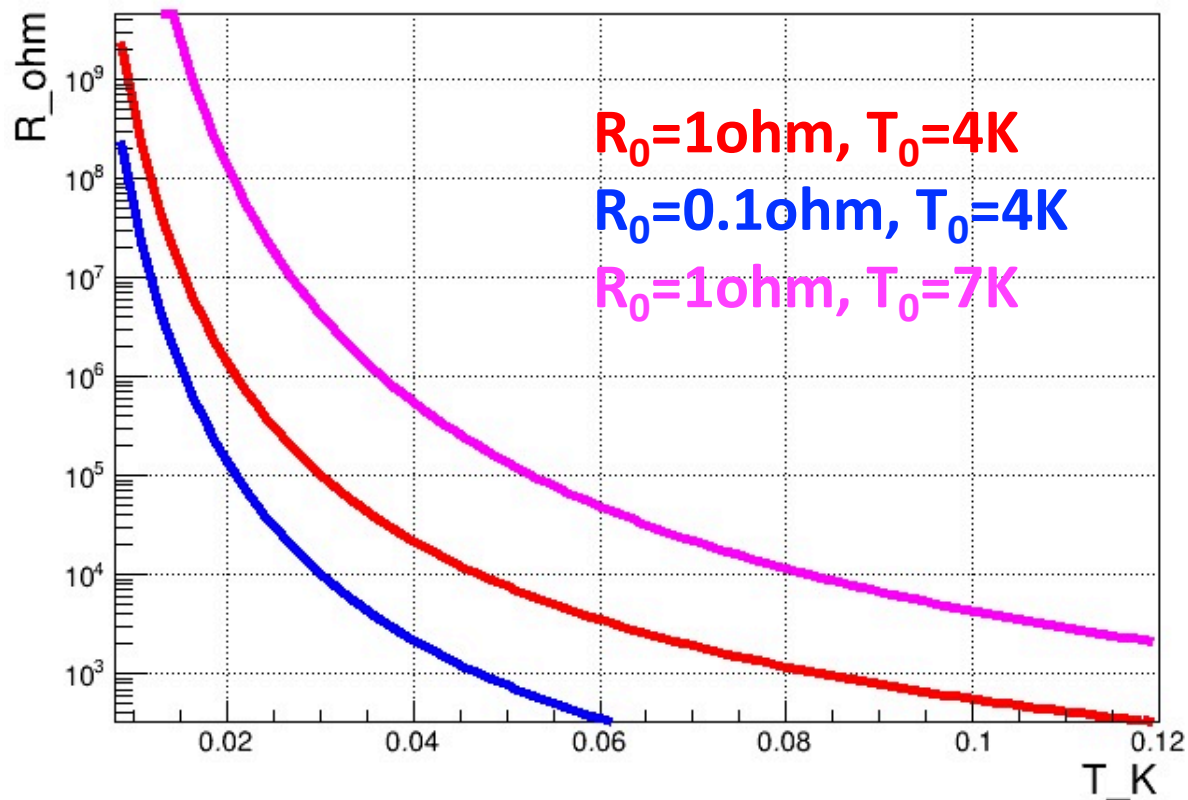
NTD，半导体辐照掺杂传感器，快速传感器'slow' sensor (ms), only sensitive to thermalized phonons



The basic idea is to utilize the different arrival times from the interaction point to different thermal sensors. **The phonon group velocity is usually few km/s. If a time resolution around $\sim 1\mu\text{s}$ can be achieved, the position accuracy will be few millimeters.** In the following, we'll discuss the possibility in detail.

The characteristic velocity of phonons is the velocity of the sound v_s ; this is the **velocity with which "vibrations" or "phonons" move through the lattice**. Typical values for solids, in particular metals, are **$v_s = (3-5) \times 10^5 \text{ cm s}^{-1}$** .

NTD参数



$$R = R_0 \exp\left(\frac{T_0}{T}\right)^\alpha$$

其中, $\alpha = 0.5$

Ge本征属性 $\rightarrow R_0$

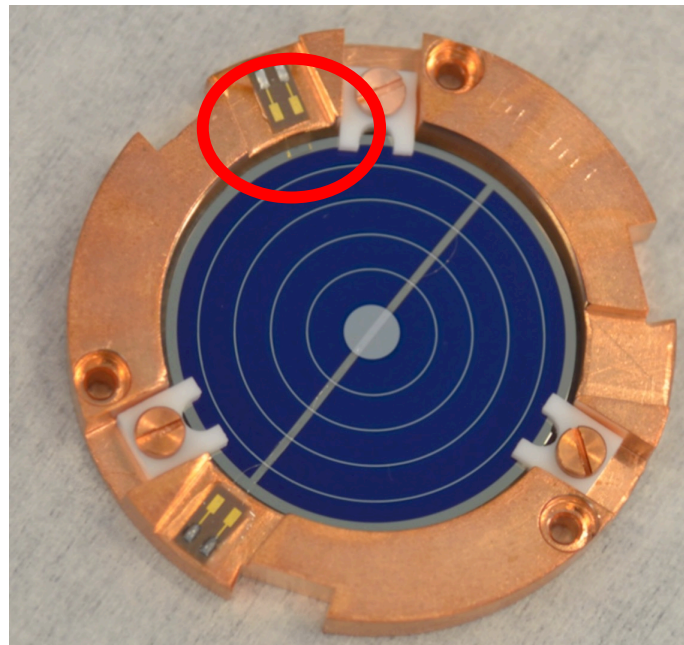
掺杂浓度 $\rightarrow \alpha$

光探测器的小尺寸NTD-Ge

A **small NTD**, with a mass of 10 mg or less, will be glued on the Ge surface using the same gluing tools as the main Li_2MoO_4 crystals. To minimize the $1/f$ noise in sliced NTDs faced over the CUPID-Mo commissioning, it will be necessary to perform a dedicated polishing of thermistors as done in CUPID-0. The use of ~ 1 mg NTDs would yield a faster response, further increase the signal amplitude, and reduce the baseline noise [39, 89].

CUPID-preCDR

[39] The **reduced size** of both the absorber and the sensor of light detectors (see Tables 3, 4) **leads to lower heat capacities and therefore to higher sensitivities**, which are in the range $\sim 1\text{--}2$ $\mu\text{V}/\text{keV}$ for a good-performance detector.

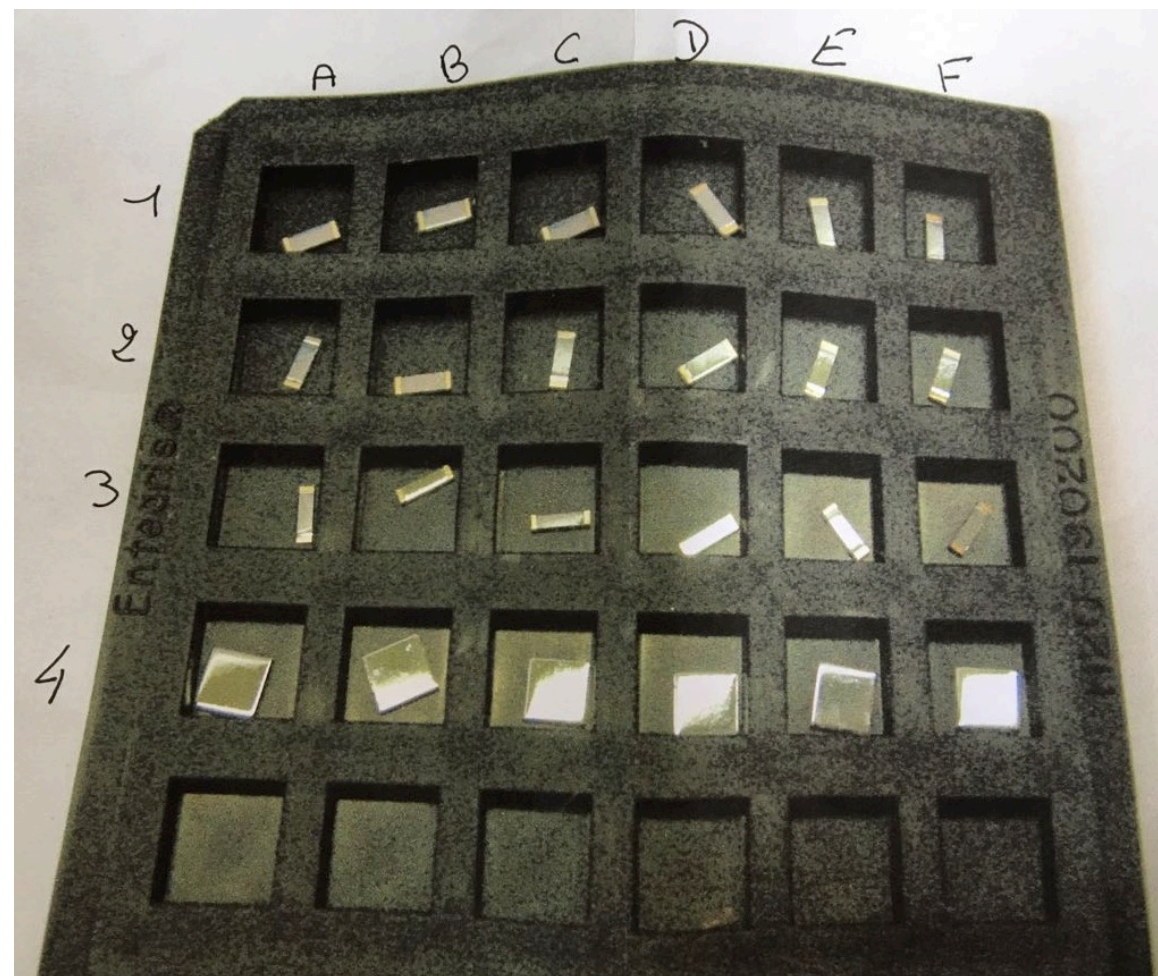


$$\Delta T = \frac{\Delta E}{C(T)}, C(T) \propto T^3$$

As for the LDs, smaller NTDs are required to increase the sensitivity. In fact, the heat capacity of the Li_2MoO_4 crystal dominates that of the NTD, while the opposite is true in the case of LDs, due to the small mass (~ 1 g) of the Ge wafer. In this case, therefore, **the mass of the NTD plays an important role**. Based on the lessons learned in CUPID-0, CUPID-Mo, and related R&D, we plan to employ NTD sensor for the LDs with a mass of about 5-10 mg and the same contact distance as the NTDs for the heat channel, but the contact cross section modified accordingly.

CUPID-preCDR

REF:	Length (mm)	width (mm)	height (μm)	weight (mg)
A1	3.025	1.160	365	6
A2	3.020	0.890	345	5
A3	3.020	0.820	300	5
B1	3.040	1.120	425	5
B2	3.040	0.930	415	4
B3	3.040	0.810	420	4
C1	3.040	1.100	435	6
C2	3.040	0.905	435	5
C3	3.040	0.800	410	4
D1	3.050	0.980	370	5
D2	3.050	0.985	370	5
D3	3.050	0.920	360	4
E1	3.060	0.945	410	5
E2	3.060	0.945	395	5
E3	3.060	0.820	430	5
F1	3.060	0.925	400	6
F2	3.060	0.915	370	5
F3	3.060	0.870	335	4
A4	3	3	530	22
B4	3	3	405	18
C4	3	3	430	19
D4	3	3	465	22
E4	3	3	430	20
F4	3	3	560	22

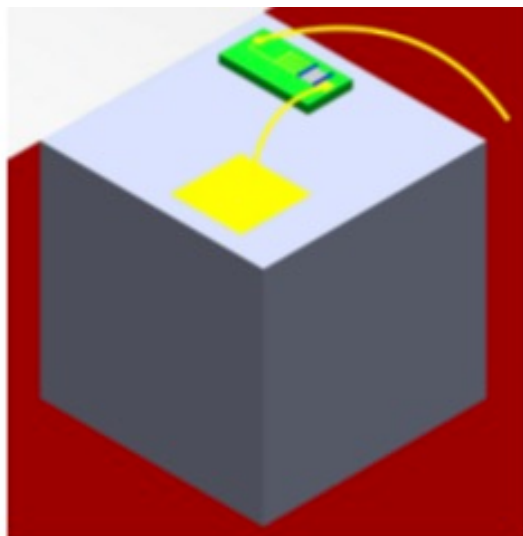


两种传感器

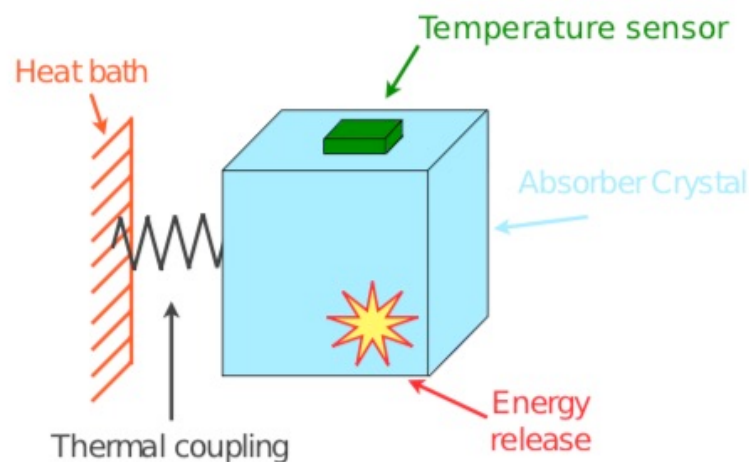
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TES+吸收体



NTD+吸收体

$$C_{total} \frac{dT}{dt} = -K_W(T - T_b) + P(t)$$

T为吸收体温度，t为时间， K_W 为热传导系数， T_b 为低温恒温器温度， $P(t)$ 是能量沉积，瞬时完成，冷却时为0。

